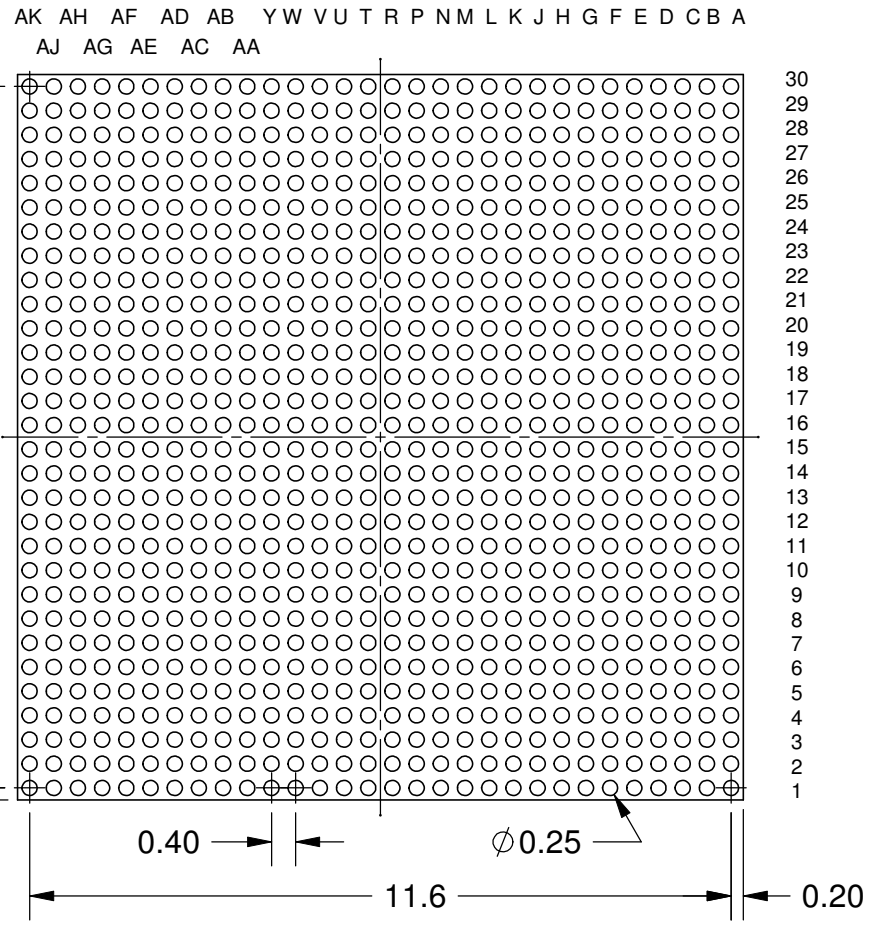
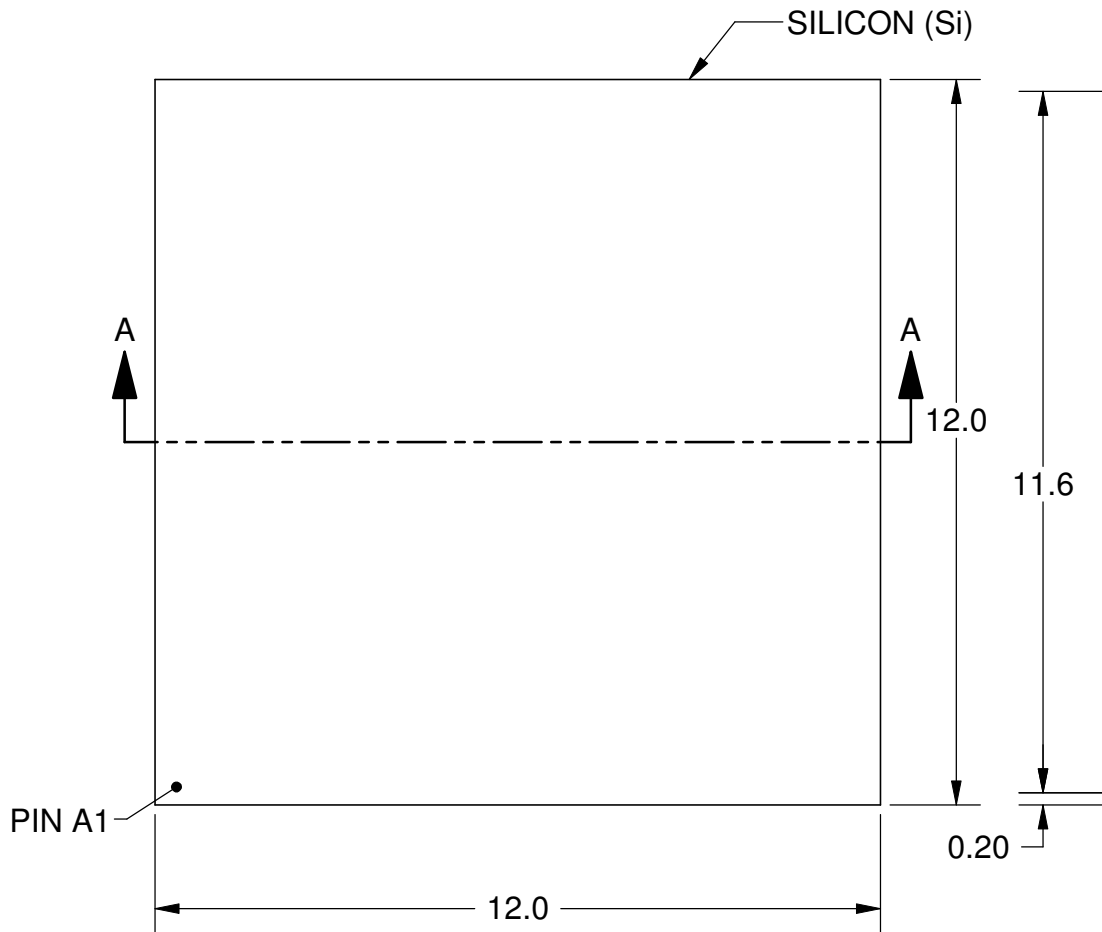
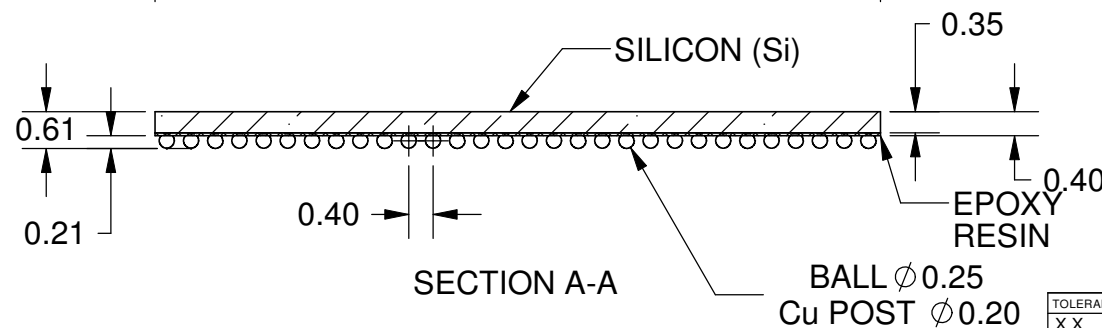


TOP VIEW

BALL VIEW



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- Notes: (Unless Otherwise Specified).
 1) ALL DIMENSIONS ARE IN MM.
 2) SOLDER BALL ALLOY:
 STANDARD: SAC305 (Sn96.5/Ag3.0/Cu0.5).
 SPECIAL: LF35 (Sn98.3/Ag1.2/Cu0.5).
 3) BALL DIAMETER (BEFORE REFLOW): 0.25mm.
 4) NON-SOLDER MASK DEFINED PAD.
 5) PAD Cu DIAMETER: 0.20mm.
 6) SUBSTRATE MATERIAL: Si (SILICON).
 7) DAISY CHAIN PATTERN (SEE PAGE 2).

PART NUMBER TABLE				
PART NUMBER	BALL ALLOY	Pb-FREE	RoHS	Si DIE
WLP900T.4C-DC307D	Sn96.5/Ag3.0/Cu0.5	YES	YES	YES
WLP900T.4C1-DC307D	Sn98.3/Ag1.2/Cu0.5	YES	YES	YES

TOLERANCE UNLESS NOTED		APPROVALS	DATE
X.X	+/- 0.3		
X.XX	+/- 0.03	DRAWN J. Hines	12/30/2010
X.XXX	+/- 0.003		
ANGLES +/- 0.5°		ENG	
ALL DIMENSIONS IN		MFG	
<input type="checkbox"/> INCHES	<input checked="" type="checkbox"/> MILLIMETERS	QA	
THIRD ANGLE PROJECTION		CUST	
		REVISED	

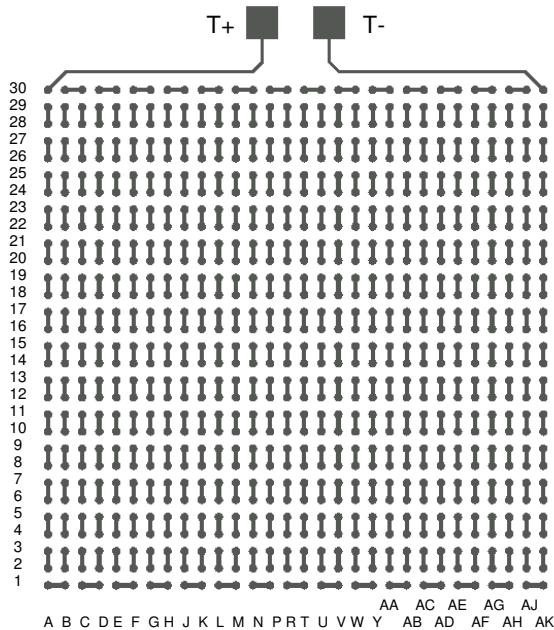
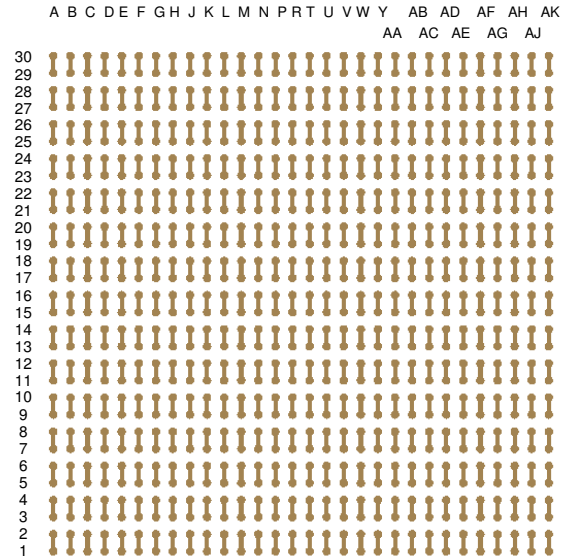
TopLine ®			
TITLE WLP900T.4C-DC307D 900-BALL P=0.4mm (TEG0408)			
SCALE 8:1	SIZE A	DRAWING NO. 543072	REV A
DO NOT SCALE DRAWING			SHEET 1 OF 2

DAISY CHAIN PATTERN



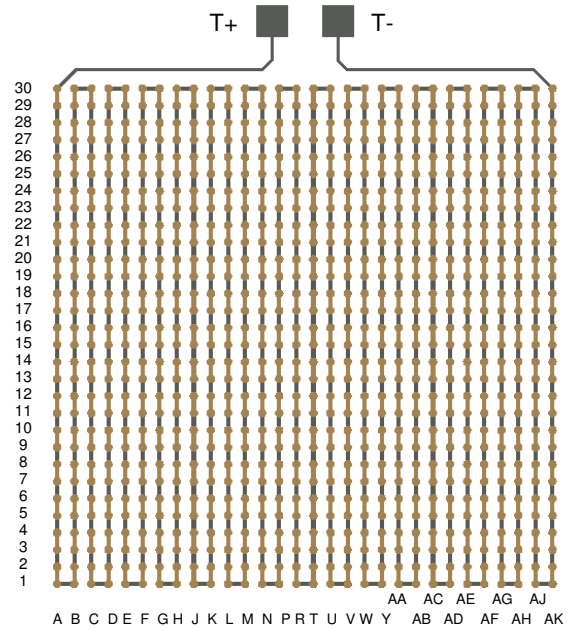
BALL VIEW

BOTTOM SIDE
(TOP X-RAY VIEW)



TOP VIEW

AFTER MOUNTING
TO TEST BOARD
(TOP X-RAY VIEW)



TEST VEHICLE BOARD

Notes:

- 1) PCB BOARD DIMENSIONS ARE PRESENTED ONLY AS A GUIDELINE. DESIGNERS SHOULD USE THEIR OWN EXPERIENCE WHEN DESIGNING PCB.
- 2) PCB Cu BALL PAD DIAMETER 0.20mm (7.8mil).
- 3) PCB DAISY CHAIN TRACING LINE WIDTH 0.10mm (3.9mil).

TopLine ®			
TITLE WLP900T.4C-DC307D 900-BALL P=0.4mm (TEG0408)			
SCALE 5.65:1	SIZE A	DRAWING NO. 543072	REV A
DO NOT SCALE DRAWING		SHEET 2 OF 2	